

the central region is an intermediate region in which no solder bumps are located. The connection solder bumps 14 are located in a peripheral region which surrounds the intermediate region of the back surface of the substrate 11a. The connection solder bumps 14 are electrically connected to electrodes of the semiconductor chip through conductive lines formed in the substrate, respectively. Therefore the connection solder bumps 14 function as terminals for connecting the semiconductor device to an outside circuit.

Please replace the paragraph on page 5, lines 10-15, with the following:

Since each of the connection solder bumps 14 is connected to one of the electrodes of the semiconductor chip, the connection solder bumps 14 should be connected to the connection pads 22 individually. Therefore, as shown in Figs. 1 and 2, the connections solder bumps are located with a predetermined pitch or distance so that the adjacent connection bumps 14 should not be joined together by the heat treatment (the joining of bumps is called a solder bridge). Figs. 1 and 2 also show that the width of the intermediate region is greater than the distance between the connection solder bumps 14.

IN THE CLAIMS:

Please amend claim 28 to read as follows: